TOSHIBA BIPOLAR DIGITAL INTEGRATED CIRCUIT SILICON MONOLITHIC

TD62304AFNG,TD62305AFNG

7CH LOW INPUT ACTIVE DARLINGTON SINK DRIVER

The TD62304AFNG and TD62305AFNG are non–inverting transistor arrays, which are comprised of seven NPN darlington buffer-transistor output stages PNP input stages.

These devices are Low Level input active drivers and are suitable for operations with a 5-V general purposed logic IC such as 5-V TTL, 5-V CMOS and 5-V Microprocessor which have sink current output drivers.

Please observe the thermal condition for using. This devices are a product for the Pb free(Sn-Ag).

FEATURES

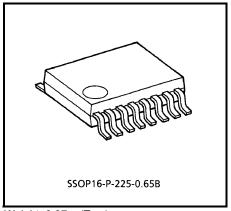
• Package Type : SSOP16 pin

• High Sustaining Voltage : VCE (SUS) = 50 V (MIN.)

Output Current (Single Output): IOUT = 500 mA / ch (MAX.)

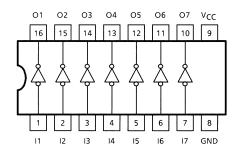
• Low Level Active Input

• Input compatible with 5-V TTL and 5-V CMOS

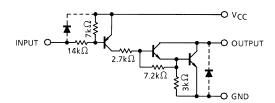


Weight: 0.07 g (Typ.)

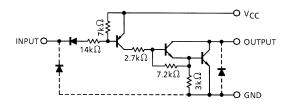
PIN CONNECTION (TOP VIEW)



SCHEMATICS (EACH DRIVER) TD62304AFNG



TD62305AFNG



Note: The input and output parasitic diodes cannot be used as clamp diodes.



MAXIMUM RATINGS (Ta = 25°C)

CHARACTERIST	SYMBOL	RATING	UNIT		
Supply Voltage	V _{CC}	-0.5~7.0	V		
Output Sustaining Voltage		V _{CE} (SUS)	-0.5~50	V	
Output Current		Гоит	500	mA / ch	
Input Voltage	TD62304	V _{IN}	-22~V _{CC} + 0.5	V	
	TD62305	VIN	-0.5~7		
Input Current	I _{IN}	-10	mA		
Power Dissipation		P _D	0.78 (Note 1)	W	
Operating Temperature		T _{opr}	-40~85	°C	
Storage Temperature	T _{stg}	-55~150	°C		

Note 1: On Glass Epoxy PCB ($50 \times 50 \times 1.6$ mm Cu 40%)

RECOMMENDED OPERATING CONDITIONS ($Ta = -40 \sim 85$ °C)

CHARACTERISTIC		SYMBOL	TEST CONDITION		MIN	TYP.	MAX	UNIT
Supply Voltage		V _{CC}			4.5	5.0	5.5	V
Output Sustaining Voltage		V _{CE (SUS)}			0	_	50	V
Output Current		IOUT (Note)	DC 1 Circuit		0	_	400	
			$T_{pw} \le 25 \text{ ms}$ 7 Circuit $Tj = 120^{\circ}\text{C}$ $Ta = 85^{\circ}\text{C}$	Duty = 10%	0	_	260	mA / ch
				Duty = 50%	0	_	65	
Input Voltage	TD62304	V _{IN}			-20	_	V_{CC}	V
	TD62305	VIIN			0	_	5.5	V
Input Voltage (Output On)	TD62304	Vin (ON)			-22	_	V _{CC} -3.5	· V
	TD62305			-0.5	_	V _{CC} -3.7		
Input Voltage (Output Off)	TD62304	.,			V _{CC} -0.4	_	V _{CC}	V
	TD62305	VIN (OFF)		V _{CC} -0.6	_	V _{CC}	V	
Power Dissipation		PD	Ta = 85°C	(Note)	_	_	0.325	W

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Note: On Glass Epoxy PCB ($50 \times 50 \times 1.6$ mm Cu 40%)

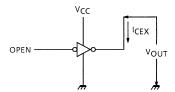


ELECTRICAL CHARACTERISTICS (Ta = 25°C)

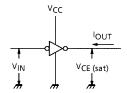
CHARACTE	RISTIC	SYMBOL	TEST CIR- CUIT	TEST CONDITION		MIN	TYP.	MAX	UNIT
Output Leakage C	Leakage Current I_{CEX} 1 $V_{CC} = 5.5 \text{ V}, V_{OUT} = 50 \text{ V}$ $Ta = 85^{\circ}\text{C}, I_{IN} = 0$			_	_	100	μΑ		
Output Saturation Voltage		V _{CE} (sat)	2	V _{CC} = 4.5 V, I _{OUT} = 350 mA	V _{IN} = V _{IN (ON)} MAX.	_	1.4	2.0	V
					V _{IN} = 0.8 V	_	1.4	2.2	
Input Current		I _{IN (ON)}	3	V _{CC} = 5.5V, V _{IN} = 0.4 V		_	-0.32	-0.45	mA
				V _{CC} = 5.5V, V _{IN} = -20 V		_	_	2.6	
Output Current	it Current I _{IN (OFF)} 4			_	_	-40	μΑ		
Output Voltage ——	TD62304	Vin (ON)	5			ı	_	V _{CC} -2.8	V
	TD62305					_	_	V _{CC} -3.7	v
Supply Current		I _{CC} (ON)	6	V _{CC} = 5.5 V, V _{IN} = 0 V		_	17	22	mA
Supply Current		I _{CC} (OFF)		V _{CC} = V _{IN} = 5.5 V		_	_	100	μA
Turn-On Delay		t _{ON}	7	V _{CC} = 5 V, C _L =	15 pF	_	0.1	_	110
Turn-Off Delay		toff] ′	$V_{OUT} = 50 \text{ V, R}_{L} = 125 \Omega$		_	3	_	μs

TEST CIRCUIT

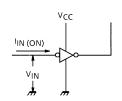
1. I_{CEX}



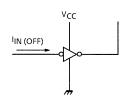
2. V_{CE (sat)}



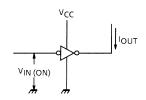
3. I_{IN (ON)}



4. I_{IN (OFF)}

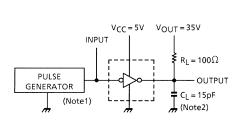


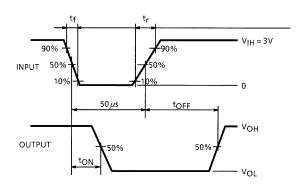
5. V_{IN (ON)}



6. I_{CC}

7. ton, toff





Note 1 Pulse Width 50 µs, Duty Cycle 10%

Output Impedance 50 Ω , $t_r \le 10$ ns, $t_f \le 5$ ns

Note 2: C_L includes probe and jig capacitance.

PRECAUTIONS for USING

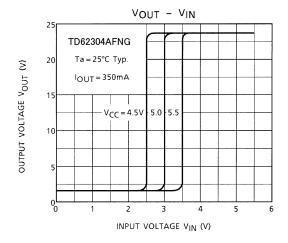
This IC does not include built-in protection circuits for excess current or overvoltage.

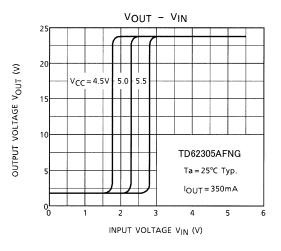
If this IC is subjected to excess current or overvoltage, it may be destroyed.

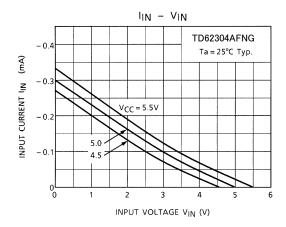
Hence, the utmost care must be taken when systems which incorporate this IC are designed.

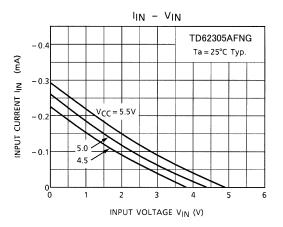
Utmost care is necessary in the design of the output line, V_{CC} and GND line since IC may be destroyed due to short–circuit between outputs, air contamination fault, or fault by improper grounding.

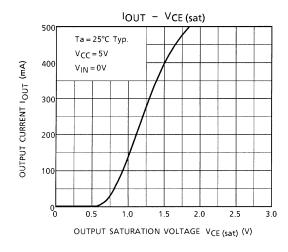
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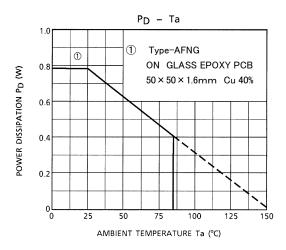








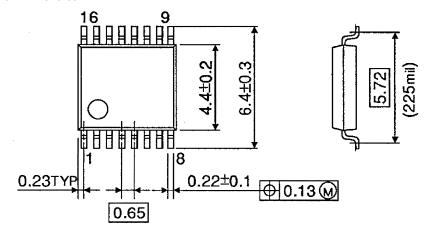


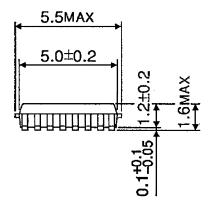


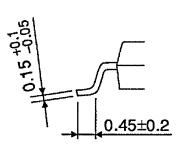
PACKAGE DIMENSIONS

SSOP16-P-225-0.65B

Unit: mm







Weight: 0.07 g (Typ.)

About solderability, following conditions were confirmed

- Solderability
 - (1) Use of Sn-63Pb solder Bath
 - solder bath temperature = 230°C
 - · dipping time = 5 seconds
 - · the number of times = once
 - · use of R-type flux
 - (2) Use of Sn-3.0Ag-0.5Cu solder Bath
 - · solder bath temperature = 245°C
 - · dipping time = 5 seconds
 - · the number of times = once
 - · use of R-type flux

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030619EBA

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